

**For Immediate Release:**

Contact:  
Bob LePage  
Marketing Manager  
Circuit Technology Center, Inc.  
Phone: 978-478-5103  
blepage@circuitrework.com  
www.circuitrework.com

**Circuit Technology Center Defines New Procedure for Rework of BGA's Underfilled with Non-reworkable Underfill Epoxy**

**February 24 2021 - Haverhill, MA, USA** - Circuit Technology Center is frequently tasked with the selective rework of BGA devices that have been underfilled with "non-reworkable" underfill epoxy. Traditional, established rework methods of using either hot gas or IR reflow technology cannot be used when non-reworkable underfills have been injected under BGA's. Circuit Technology Center developed a reliable process to solve this challenging application and provided details in a new guidebook procedure.

For more information see the guidebook procedure at: <https://www.circuitrework.com/guides/9-5-1.html>

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Circuit Technology Center, founded in 1979, continues to be recognized as the most innovative and reliable specialist in circuit board damage repair, rework, BGA re-balling and component level modification services in the world.

For more information, please visit: [www.circuitrework.com](http://www.circuitrework.com). Phone: 978-374-5000, Fax: 978-372-5700, Web: [www.circuitrework.com](http://www.circuitrework.com).